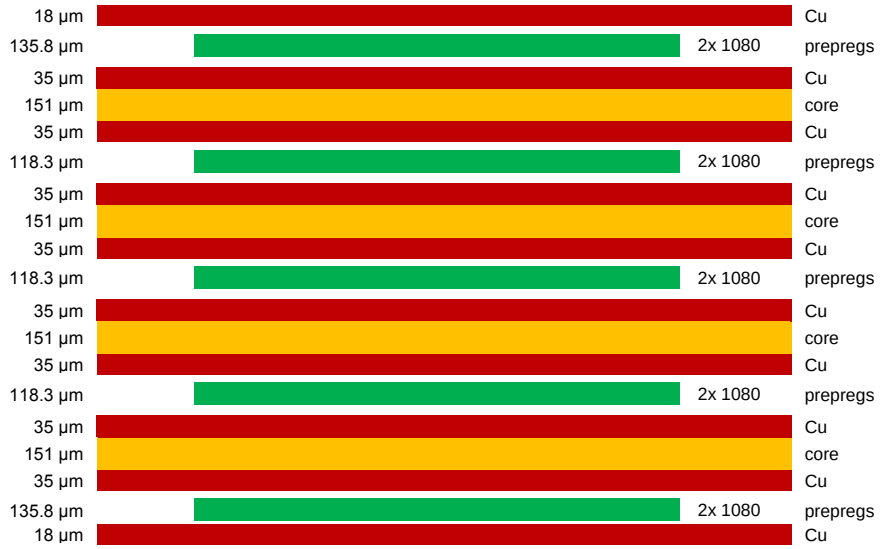
10-layer PCB stackup



Parameters

material type:	Standard FR4 TG130
base materials thickness (after lamination):	1.547 mm
final PCB thickness:	1.72 mm ±0.14 mm
Cu thickness:	
outer layers (base thickness, without plating):	18 µm
inner layers (final thickness):	35 µm / 35 µm / 35 µm / 35 µm / 35 µm / 35 µm / 35 µm / 35 µm